



Chip Card & Security ICs

SLE 5542

Intelligent 256-Byte EEPROM
with Write Protection function
and Programmable Security Code

SLE 5542 Short Product Information		Ref.: SPI_SLE5542_0506.doc
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Page	Subjects (changes since last revision)	
all	Editorial changes	

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Information

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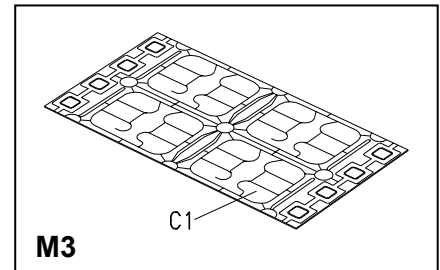
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Intelligent 256-Byte EEPROM with Write Protection Function and Programmable Security Code (PSC)

Features

- **100% functional compatibility to SLE 4442**
- **256 x 8 bit EEPROM organization of Data Memory**
- **32 x 1 bit Protection Memory**
 - Byte-wise write protection of first 32 addresses (byte 0...31) of Data Memory
 - Manufacturer Code for unique identification of application
- **Data Memory (addresses 0...255) alterable only after verification of 3-Byte Programmable Security Code (PSC)**
- **Two-wire link protocol**
 - Byte-wise addressing
 - End of processing indicated at data output
- **Contact configuration and Answer-to-Reset (synchronous transmission) in accordance to standard ISO/IEC 7816**
- **Sophisticated electrical characteristics**
 - Ambient temperature $-40 \dots +80^{\circ}\text{C}$ for chip, $-25 \dots +80^{\circ}\text{C}$ for module
 - Supply voltage $5 \text{ V} \pm 10 \%$
 - Supply current $< 3 \text{ mA}$ (typical $600 \mu\text{A}$)
 - EEPROM erase / write time 5 ms
 - ESD protection typical $4,000 \text{ V}$
 - EEPROM Endurance minimum $100,000$ erase / write cycles¹⁾
 - Data retention for minimum of 10 years ¹⁾
- **Advanced $1.2 \mu\text{m}$ CMOS-technology optimised for security layout**
 - EEPROM-cells protected by shield
 - Shielding of deeper layers via metal
 - Sensory and logical security functions
 - No isolation on backside necessary



¹⁾ Values are temperature dependent.

1 Ordering and Packaging information

Table 1 Ordering Information

Type	Package ¹⁾	Remark	Ordering Code
SLE 5542 C	Die (on Wafer)	unsawn	on request
SLE 5542 D	Die (on Wafer)	sawn	on request
SLE 5542 M3	T-M3.2-6		on request
SLE 5542 MFC3	S-MFC3.1-6-1	FCoS™	on request

Pin Description

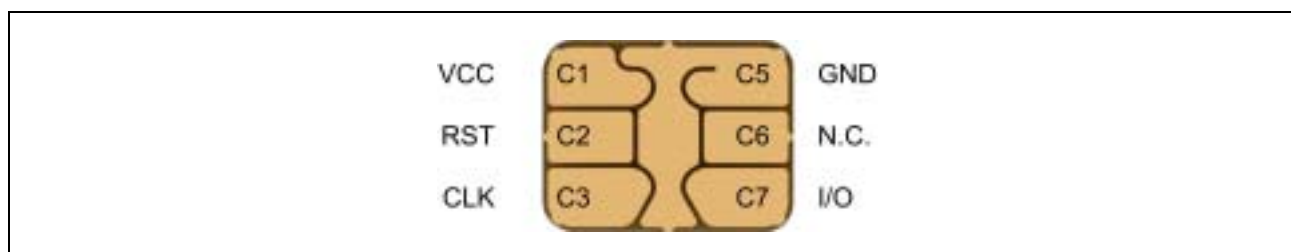


Figure 1 Pin Configuration Wire-bonded Module M3.2 (top view)

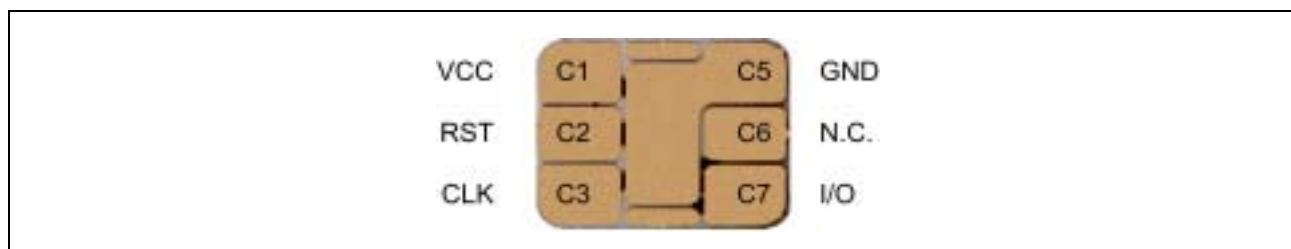


Figure 2 Pin Configuration Module Flip Chip MFC3.1 (top view)

¹⁾ Available as a Module Flip Chip (MFC3), wire-bonded module (M3) for embedding in plastic cards or as a die on unsawn (C) / sawn wafer (D) for customer packaging



Figure 3 Pad Configuration Die

Table 2 Pin Definitions and Functions

Card Contact	Symbol	Function
C1	VCC	Supply voltage
C2	RST	Control input (Reset Signal)
C3	CLK	Clock input
C5	GND	Ground
C6	N.C.	Not connected
C7	I/O	Bi-directional data line (open drain)

2 Circuit Description

Memory Organization

The memory is organized in a **Data Memory** of 256 byte.

Write Protection of Data Memory

Each of the first 32 bytes of the Data Memory can be irreversibly protected against data change by writing the corresponding bit in the **Protection Memory** (32 bit). Dependent on the state of the protection bit the Data Memory is read only (ROM) or may be erased and written again (EEPROM). Change of the manufacturer code (Application ID and Chip Coding) is only possible by the chip manufacturer.

Programmable Security Code

Change of data of the Data Memory and write a bit of the Protection Memory is only possible after verification of the 3-Byte **Programmable Security Code (PSC).**

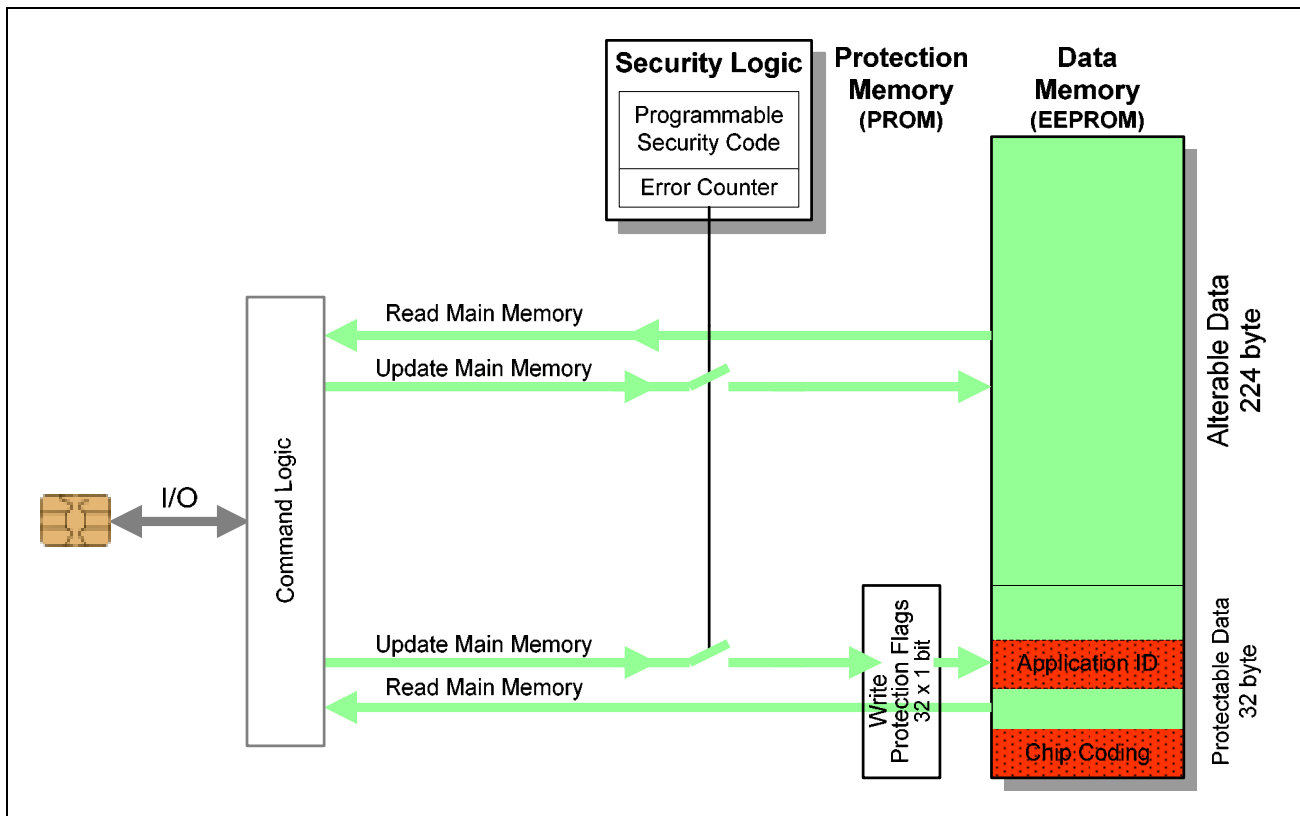


Figure 4 Memory Overview SLE 5542